



**THE DATASHEET OF  
74AUP1G02SE-7**



## Description

The advanced ultra-low power (AUP) CMOS logic family is designed for low power and extended battery life in portable applications.

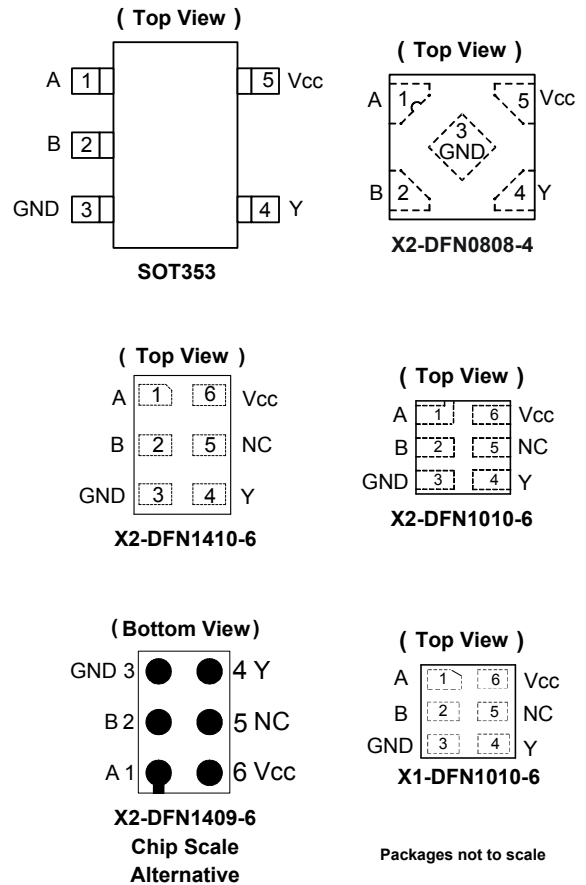
The 74AUP1G02 is a single, two-input, positive NOR gate with a standard push-pull output designed for operation over a power supply range of 0.8V to 3.6V. The device is fully specified for partial power-down applications using I<sub>OFF</sub>. The I<sub>OFF</sub> circuitry disables the output, preventing damaging current backflow when the device is powered down. The gate performs the positive Boolean function:

$$Y = \overline{A + B} \text{ or } Y = \overline{A} \cdot \overline{B}$$

## Features

- Advanced Ultra Low Power (AUP) CMOS
- Supply Voltage Range from 0.8V to 3.6V
- ±4mA Output Drive at 3.0V
- Low Static Power Consumption  
I<sub>CC</sub> < 0.9µA
- Low Dynamic Power Consumption  
C<sub>PD</sub> = 6.4pF (Typical at 3.6V)
- Schmitt trigger action at all inputs makes the circuit tolerant for slower input rise and fall time. The hysteresis is typically 250mV at V<sub>CC</sub> = 3.0V.
- I<sub>OFF</sub> Supports Partial Power-Down Mode Operation
- ESD Protection Exceeds JESD 22  
2000V Human Body Model (A114)  
Exceeds 1000V Charged Device Model (C101)
- Latch-Up Exceeds 100mA per JESD 78, Class I
- Leadless Packages Named per JESD30E
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please [contact us](mailto:contact@diodes.com) or your local Diodes representative**  
<https://www.diodes.com/quality/product-definitions/>

## Pin Assignments

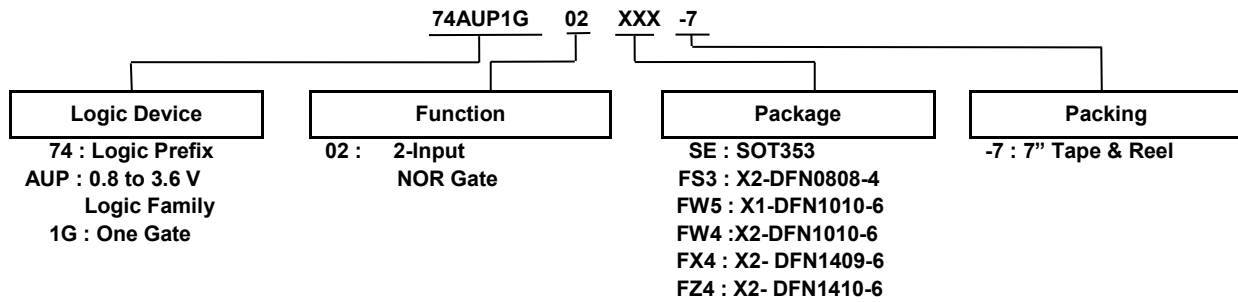


## Applications

- Suited for Battery and Low-Power Requirements
- Wide Array of Products such as:
  - Tablets, E-Readers
  - Cell Phones, Personal Navigation/GPS Systems
  - MP3 Players, Cameras, Video Recorders
  - PCs, Ultrabook™, Notebooks, Netbooks,
  - Computer Peripherals, Hard Drives, SSDs, CD/DVD ROMs
  - TVs, DVDs, DVRs, Set-Top Boxes

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.  
2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.  
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

## Ordering Information



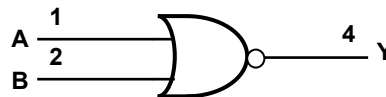
Device	Package Code	Package (Notes 4 & 5)	Package Size	7" Tape and Reel	
				Quantity	Part Number Suffix
74AUP1G02SE-7	SE	SOT353	2.15mm x 2.1mm x 1.1mm 0.65mm lead pitch	3000/Tape & Reel	-7
74AUP1G02FS3-7	FS3	X2-DFN0808-4	0.8mm x 0.8mm x 0.30mm 0.5mm pad pitch (diamond)	5000/Tape & Reel	-7
74AUP1G02FW5-7	FW5	X1-DFN1010-6	1.0mm x 1.0mm x 0.5mm 0.35mm pad pitch	5000/Tape & Reel	-7
74AUP1G02FW4-7	FW4	X2-DFN1010-6	1.0mm x 1.0mm x 0.4mm 0.35mm pad pitch	5000/Tape & Reel	-7
74AUP1G02FX4-7	FX4	X2-DFN1409-6 Chip Scale Alternative	1.4mm x 0.9mm x 0.4mm 0.5mm pad pitch	5000/Tape & Reel	-7
74AUP1G02FZ4-7	FZ4	X2-DFN1410-6	1.4mm x 1.0mm x 0.4mm 0.5mm pad pitch	5000/Tape & Reel	-7

Notes: 4. Pad layout, as shown in Diodes Incorporated suggested pad layouts, can be found at <http://www.diodes.com/package-outlines.html>.  
 5. The taping orientation is located on our website at <https://www.diodes.com/assets/Packaging-Support-Docs/ap02007.pdf>

## Pin Descriptions

Pin Name	Function
A	Data Input
B	Data Input
GND	Ground
Y	Data Output
V <sub>CC</sub>	Supply Voltage

## Logic Diagram



## Function Table

Inputs		Output
A	B	Y
L	L	H
L	H	L
H	L	L
H	H	L

**Absolute Maximum Ratings** (Notes 6 & 7) (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Symbol	Parameter	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	kV
ESD CDM	Charged Device Model ESD Protection	1	kV
$V_{CC}$	Supply Voltage Range	-0.5 to +4.6	V
$V_I$	Input Voltage Range	-0.5 to +4.6	V
$V_O$	Voltage Applied to Output in High or Low State	-0.5 to $V_{CC} + 0.5$	V
$I_{IK}$	Input Clamp Current $V_I < 0$	50	mA
$I_{OK}$	Output Clamp Current ( $V_O < 0$ )	50	mA
$I_O$	Continuous Output Current ( $V_O = 0$ to $V_{CC}$ )	$\pm 20$	mA
$I_{CC}$	Continuous Current through $V_{CC}$	50	mA
$I_{GND}$	Continuous Current through GND	-50	mA
$T_J$	Operating Junction Temperature	-40 to +150	$^\circ\text{C}$
$T_{STG}$	Storage Temperature	-65 to +150	$^\circ\text{C}$

- Notes:
- Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.
  - Forcing the maximum allowed voltage could cause a condition exceeding the maximum current or conversely forcing the maximum current could cause a condition exceeding the maximum voltage. The ratings of both current and voltage must be maintained within the controlled range.

**Recommended Operating Conditions** (Note 8) (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Symbol	Parameter	Min	Max	Unit		
$V_{CC}$	Operating Voltage	0.8	3.6	V		
$V_I$	Input Voltage	0	3.6	V		
$V_O$	Output Voltage	0	$V_{CC}$	V		
$I_{OH}$	High-Level Output Current	$V_{CC} = 0.8\text{V}$	—	-20	$\mu\text{A}$	
		$V_{CC} = 1.1\text{V}$	—	-1.1	mA	
		$V_{CC} = 1.4\text{V}$	—	-1.7		
		$V_{CC} = 1.65\text{V}$	—	-1.9		
		$V_{CC} = 2.3\text{V}$	—	-3.1		
		$V_{CC} = 3.0\text{V}$	—	-4		
$I_{OL}$	Low-Level Output Current	$V_{CC} = 0.8\text{V}$	—	20	$\mu\text{A}$	
		$V_{CC} = 1.1\text{V}$	—	1.1	mA	
		$V_{CC} = 1.4\text{V}$	—	1.7		
		$V_{CC} = 1.65\text{V}$	—	1.9		
		$V_{CC} = 2.3\text{V}$	—	3.1		
		$V_{CC} = 3.0\text{V}$	—	4		
$\Delta t/\Delta V$	Input Transition Rise or Fall Rate	$V_{CC} = 0.8\text{V}$ to $3.6\text{V}$		—	200	ns/V
$T_A$	Operating Free-Air Temperature	-40	+125	$^\circ\text{C}$		

- Note: 8. Unused inputs should be held at  $V_{CC}$  or Ground.

**Electrical Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Symbol	Parameter	Test Conditions	$V_{CC}$	$T_A = +25^\circ\text{C}$		$T_A = -40^\circ\text{C to } +85^\circ\text{C}$		Unit
				Min	Max	Min	Max	
$V_{IH}$	High-Level Input Voltage	—	0.8V to 1.65V	$0.80 \times V_{CC}$	—	$0.80 \times V_{CC}$	—	V
		—	1.65V to 1.95V	$0.65 \times V_{CC}$	—	$0.65 \times V_{CC}$	—	
		—	2.3V to 2.7V	1.6	—	1.6	—	
		—	3.0V to 3.6V	2.0	—	2.0	—	
$V_{IL}$	Low-Level Input Voltage	—	0.8V to 1.65V	—	$0.30 \times V_{CC}$	—	$0.30 \times V_{CC}$	V
		—	1.65V to 1.95V	—	$0.35 \times V_{CC}$	—	$0.35 \times V_{CC}$	
		—	2.3V to 2.7V	—	0.7	—	0.7	
		—	3.0V to 3.6V	—	0.9	—	0.9	
$V_{OH}$	High-Level Output Voltage	$I_{OH} = -20\mu\text{A}$	0.8V to 3.6V	$V_{CC} - 0.1$	—	$V_{CC} - 0.1$	—	V
		$I_{OH} = -1.1\text{mA}$	1.1V	$0.75 \times V_{CC}$	—	$0.7 \times V_{CC}$	—	
		$I_{OH} = -1.7\text{mA}$	1.4V	1.11	—	1.03	—	
		$I_{OH} = -1.9\text{mA}$	1.65V	1.32	—	1.3	—	
		$I_{OH} = -2.3\text{mA}$	2.3V	2.05	—	1.97	—	
		$I_{OH} = -3.1\text{mA}$		1.9	—	1.85	—	
		$I_{OH} = -2.7\text{mA}$	3V	2.72	—	2.67	—	
		$I_{OH} = -4\text{mA}$		2.6	—	2.55	—	
$V_{OL}$	Low-Level Output Voltage	$I_{OL} = 20\mu\text{A}$	0.8V to 3.6V	—	0.1	—	0.1	V
		$I_{OL} = 1.1\text{mA}$	1.1V	—	$0.3 \times V_{CC}$	—	$0.3 \times V_{CC}$	
		$I_{OL} = 1.7\text{mA}$	1.4V	—	0.31	—	0.37	
		$I_{OL} = 1.9\text{mA}$	1.65V	—	0.31	—	0.35	
		$I_{OL} = 2.3\text{mA}$	2.3V	—	0.31	—	0.33	
		$I_{OL} = 3.1\text{mA}$		—	0.44	—	0.45	
		$I_{OL} = 2.7\text{mA}$	3V	—	0.31	—	0.33	
		$I_{OL} = 4\text{mA}$		—	0.44	—	0.45	
$I_I$	Input Current	A or B Input $V_I = \text{GND to } 3.6\text{V}$	0 to 3.6V	—	$\pm 0.1$	—	$\pm 0.5$	$\mu\text{A}$
$I_{OFF}$	Power Down Leakage Current	$V_I$ or $V_O = 0\text{V to } 3.6\text{V}$	0	—	0.2	—	0.6	$\mu\text{A}$
$\Delta I_{OFF}$	Delta Power Down Leakage Current	$V_I$ or $V_O = 0\text{V to } 3.6\text{V}$	0V to 0.2V	—	0.2	—	0.6	$\mu\text{A}$
$I_{CC}$	Supply Current	$V_I = \text{GND or } V_{CC}, I_O = 0$	0.8V to 3.6V	—	0.5	—	0.9	$\mu\text{A}$
$\Delta I_{CC}$	Additional Supply Current	One Input at $V_{CC} - 0.6\text{V}$ Other Inputs at $V_{CC}$ or GND	3.3V	—	40	—	50	$\mu\text{A}$

**Electrical Characteristics** (continued) (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Symbol	Parameter	Test Conditions	V <sub>CC</sub>	T <sub>A</sub> = -40°C to +125°C		Unit
				Min	Max	
V <sub>IH</sub>	High-Level Input Voltage	—	0.8V to 1.65V	0.80 x V <sub>CC</sub>	—	V
		—	1.65V to 1.95V	0.70 x V <sub>CC</sub>	—	
		—	2.3V to 2.7V	1.6	—	
		—	3.0V to 3.6V	2.0	—	
V <sub>IL</sub>	Low-Level Input Voltage	—	0.8V to 1.65V	—	0.25 x V <sub>CC</sub>	V
		—	1.65V to 1.95V	—	0.30 x V <sub>CC</sub>	
		—	2.3V to 2.7V	—	0.7	
		—	3.0V to 3.6V	—	0.9	
V <sub>OH</sub>	High-Level Output Voltage	I <sub>OH</sub> = -20 μA	0.8V to 3.6V	V <sub>CC</sub> - 0.11	—	V
		I <sub>OH</sub> = -1.1 mA	1.1V	0.6 x V <sub>CC</sub>	—	
		I <sub>OH</sub> = -1.7 mA	1.4V	0.93	—	
		I <sub>OH</sub> = -1.9 mA	1.65V	1.17	—	
		I <sub>OH</sub> = -2.3 mA	2.3V	1.77	—	
		I <sub>OH</sub> = -3.1 mA		1.67	—	
		I <sub>OH</sub> = -2.7 mA	3V	2.40	—	
		I <sub>OH</sub> = -4 mA		2.30	—	
V <sub>OL</sub>	Low-Level Output Voltage	I <sub>OL</sub> = 20 μA	0.8V to 3.6V	—	0.11	V
		I <sub>OL</sub> = 1.1 mA	1.1V	—	0.33 x V <sub>CC</sub>	
		I <sub>OL</sub> = 1.7 mA	1.4V	—	0.41	
		I <sub>OL</sub> = 1.9 mA	1.65V	—	0.39	
		I <sub>OL</sub> = 2.3 mA	2.3V	—	0.36	
		I <sub>OL</sub> = 3.1 mA		—	0.50	
		I <sub>OL</sub> = 2.7 mA	3V	—	0.36	
		I <sub>OL</sub> = 4 mA		—	0.50	
I <sub>I</sub>	Input Current	A or B Input V <sub>I</sub> = GND to 3.6V	0 to 3.6V	—	± 0.75	μA
I <sub>OFF</sub>	Power Down Leakage Current	V <sub>I</sub> or V <sub>O</sub> = 0V to 3.6V	0	—	± 3.5	μA
ΔI <sub>OFF</sub>	Delta Power Down Leakage Current	V <sub>I</sub> or V <sub>O</sub> = 0V to 3.6V	0V to 0.2V	—	± 2.5	μA
I <sub>CC</sub>	Supply Current	V <sub>I</sub> = GND or V <sub>CC</sub> , I <sub>O</sub> = 0	0.8V to 3.6V	—	3.0	μA
ΔI <sub>CC</sub>	Additional Supply Current	Input at V <sub>CC</sub> - 0.6V Other Inputs at V <sub>CC</sub> or GND	3.3V	—	75	μA

**Switching Characteristics**
 $C_L = 5\text{pF}$ , See Figure 1

Parameter	From Input	TO OUTPUT	V <sub>CC</sub>	T <sub>A</sub> = +25°C			T <sub>A</sub> = -40°C to +85°C		T <sub>A</sub> = -40°C to +125°C		Unit
				Min	Typ	Max	Min	Max	Min	Max	
t <sub>pd</sub>	A or B	Y	0.8V	—	17.0	—	—	—	—	—	ns
			1.2V ± 0.1V	2.5	5.1	10.8	2.1	12.1	2.1	13.4	
			1.5V ± 0.1V	1.6	3.7	6.7	1.4	7.8	1.4	8.6	
			1.8V ± 0.15V	1.3	3.0	5.3	1.1	6.2	1.1	6.9	
			2.5V ± 0.2V	1.0	2.4	3.9	0.9	4.6	0.9	5.1	
			3.3V ± 0.3V	1.0	2.2	3.4	0.8	4.0	0.8	4.4	

 $C_L = 10\text{pF}$ , See Figure 1

Parameter	From Input	To Output	V <sub>CC</sub>	T <sub>A</sub> = +25°C			T <sub>A</sub> = -40°C to +85°C		T <sub>A</sub> = -40°C to +125°C		Unit
				Min	Typ	Max	Min	Max	Min	Max	
t <sub>pd</sub>	A or B	Y	0.8V	—	20.4	—	—	—	—	—	ns
			1.2V ± 0.1V	2.4	6.0	12.8	2.2	14.3	2.2	15.8	
			1.5V ± 0.1V	1.9	4.3	7.9	1.7	9.2	1.7	10.2	
			1.8V ± 0.15V	1.6	3.6	6.2	1.5	7.3	1.5	8.1	
			2.5V ± 0.2V	1.4	3.0	4.7	1.2	5.6	1.2	6.2	
			3.3V ± 0.3V	1.3	2.7	4.2	1.2	5.0	1.2	5.5	

 $C_L = 15\text{pF}$ , See Figure 1

Parameter	From Input	To Output	V <sub>CC</sub>	T <sub>A</sub> = +25°C			T <sub>A</sub> = -40°C to +85°C		T <sub>A</sub> = -40°C to +125°C		Unit
				Min	Typ	Max	Min	Max	Min	Max	
t <sub>pd</sub>	A or B	Y	0.8V	—	23.9	—	—	—	—	—	ns
			1.2V ± 0.1V	3.4	6.8	14.6	3.1	16.4	3.1	18.1	
			1.5V ± 0.1V	2.3	4.8	8.9	2.0	10.4	2.0	11.5	
			1.8V ± 0.15V	1.9	4.0	7.0	1.7	8.3	1.7	9.2	
			2.5V ± 0.2V	1.7	3.4	5.4	1.5	6.3	1.5	7.0	
			3.3V ± 0.3V	1.6	3.2	4.8	1.4	5.7	1.4	6.3	

 $C_L = 30\text{pF}$ , See Figure 1

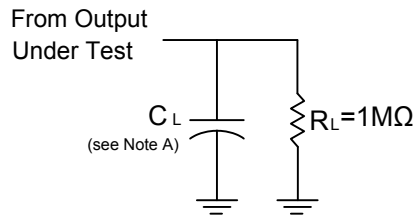
Parameter	From Input	To Output	V <sub>CC</sub>	T <sub>A</sub> = +25°C			T <sub>A</sub> = -40°C to +85°C		T <sub>A</sub> = -40°C to +125°C		Unit
				Min	Typ	Max	Min	Max	Min	Max	
t <sub>pd</sub>	A or B	Y	0.8V	—	34.2	—	—	—	—	—	ns
			1.2V ± 0.1V	4.6	19.0	22.0	4.1	22.4	4.1	24.7	
			1.5V ± 0.1V	3.4	6.4	11.8	2.9	13.9	2.9	15.3	
			1.8V ± 0.15V	2.6	5.3	9.3	2.3	11.1	2.3	12.3	
			2.5V ± 0.2V	2.4	4.5	7.1	2.1	8.5	2.1	9.4	
			3.3V ± 0.3V	2.0	2.9	6.4	2.1	7.7	2.1	8.5	

**Operating and Package Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

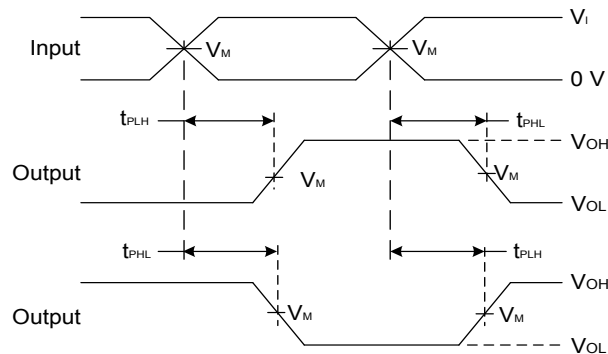
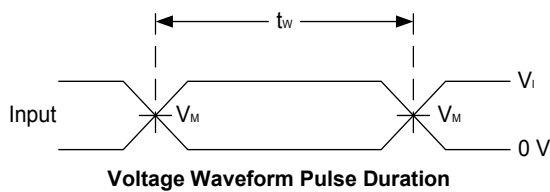
Parameter		Test Conditions		$V_{CC}$	Typ	Unit
$C_{pd}$	Power Dissipation Capacitance	f = 1MHz No Load		0.8V	6.8	pF
				$1.2V \pm 0.1V$	6.7	
				$1.5V \pm 0.1V$	6.6	
				$1.8V \pm 0.15V$	6.2	
				$2.5V \pm 0.2V$	6.5	
				$3.3V \pm 0.3V$	6.4	
$C_i$	Input Capacitance	$V_i = V_{CC}$ or GND		0V or 3.3V	1.5	pF
$\theta_{JA}$	Thermal Resistance Junction-to-Ambient	SOT353	(Note 9)	—	371	$^\circ\text{C/W}$
		X2-DFN0808-4		—	430	
		X1-DFN1010-6		—	435	
		X2-DFN1010-6		—	445	
		X2-DFN1409-6		—	470	
		X2-DFN1410-6		—	460	
$\theta_{JC}$	Thermal Resistance Junction-to-Case	SOT353	(Note 9)	—	143	$^\circ\text{C/W}$
		X2-DFN0808-4		—	240	
		X1-DFN1010-6		—	250	
		X2-DFN1010-6		—	250	
		X2-DFN1409-6		—	275	
		X2-DFN1410-6		—	265	

Note: 9. Test condition for each of the six package types: Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

**Parameter Measurement Information**



Vcc	Inputs		V <sub>M</sub>	C <sub>L</sub>
	V <sub>I</sub>	t <sub>r</sub> /t <sub>f</sub>		
0.8V	V <sub>CC</sub>	≤3ns	V <sub>CC</sub> /2	5, 10, 15, 30pF
1.2V±0.1V	V <sub>CC</sub>	≤3ns	V <sub>CC</sub> /2	5, 10, 15, 30pF
1.5V±0.1V	V <sub>CC</sub>	≤3ns	V <sub>CC</sub> /2	5, 10, 15, 30pF
1.8V ±0.15V	V <sub>CC</sub>	≤3ns	V <sub>CC</sub> /2	5, 10, 15, 30pF
2.5V±0.2V	V <sub>CC</sub>	≤3ns	V <sub>CC</sub> /2	5, 10, 15, 30pF
3.3V±0.3V	V <sub>CC</sub>	≤3ns	V <sub>CC</sub> /2	5, 10, 15, 30pF



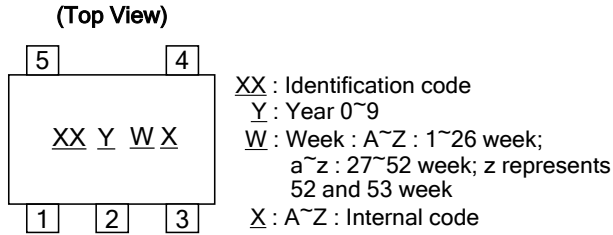
**Voltage Waveform Propagation Delay Times  
Inverting and Non Inverting Outputs**

**Figure 1 Load Circuit and Voltage Waveforms**

- Notes:
- A. Includes test lead and test apparatus capacitance.
  - B. All pulses are supplied at pulse repetition rate ≤ 10MHz.
  - C. Inputs are measured separately one transition per measurement.
  - D. t<sub>PLH</sub> and t<sub>PHL</sub> are the same as t<sub>PD</sub>.

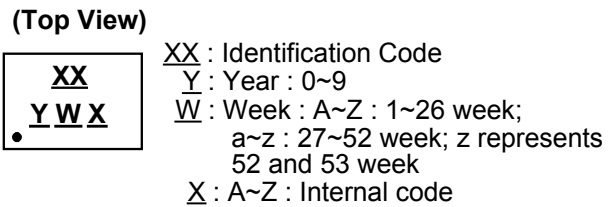
**Marking Information**

(1) SOT353



Part Number	Package	Identification Code
74AUP1G02SE-7	SOT353	XJ

(2) X2-DFN0808-4, X1-DFN1010-6, X2-DFN1010-6, X2-DFN1409-6 and X2-DFN1410-6

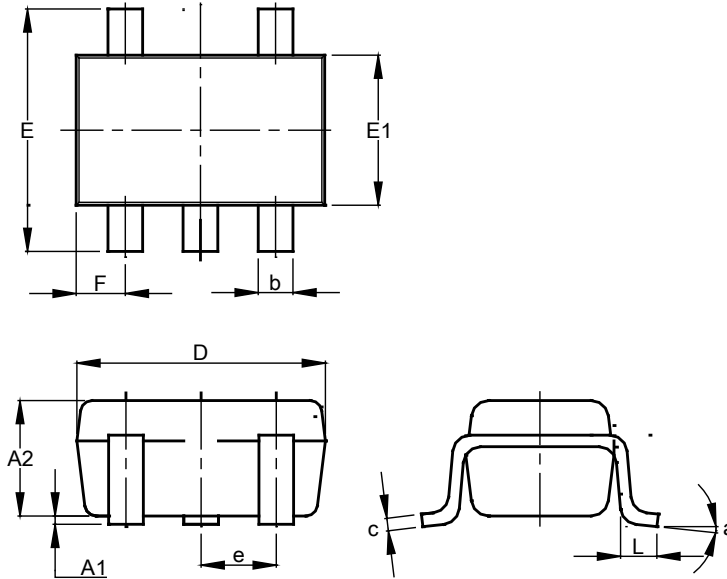


Part Number	Package	Identification Code
74AUP1G02FS3-7	X2-DFN0808-4	YP
74AUP1G02FW5-7	X1-DFN1010-6	Q3
74AUP1G02FW4-7	X2-DFN1010-6	XJ
74AUP1G02FX4-7	X2-DFN1409-6	HB
74AUP1G02FZ4-7	X2-DFN1410-6	XJ

**SOT353 Package Outline Dimensions and Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version

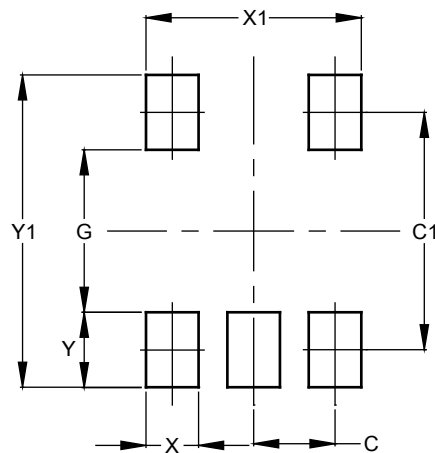
SOT353



SOT353			
Dim	Min	Max	Typ
A1	0.00	0.10	0.05
A2	0.90	1.00	0.95
b	0.10	0.30	0.25
c	0.10	0.22	0.11
D	1.80	2.20	2.15
E	2.00	2.20	2.10
E1	1.15	1.35	1.30
e	0.650 BSC		
F	0.40	0.45	0.425
L	0.25	0.40	0.30
a	0°	8°	--
All Dimensions in mm			

**Suggested Pad Layout**

SOT353

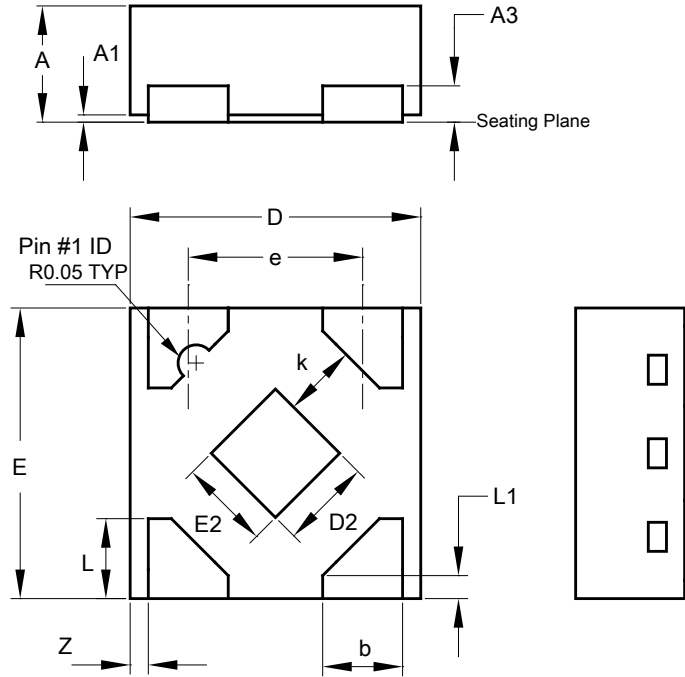


Dimensions	Value (in mm)
C	0.650
C1	1.900
G	1.300
X	0.420
X1	1.720
Y	0.600
Y1	2.500

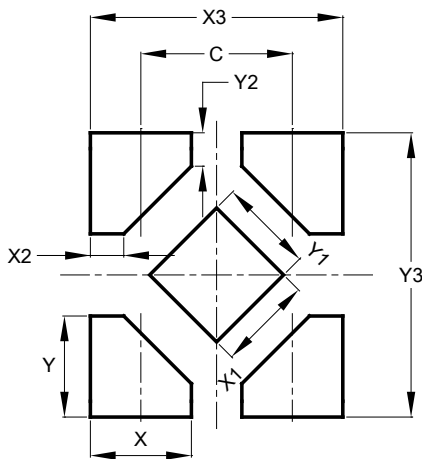
SOT353 Package Information  
Rev. 2018-01-16

**X2-DFN0808-4 Package Outline Dimensions and Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version



X2-DFN0808-4			
Dim	Min	Max	Typ
A	0.25	0.35	0.30
A1	0	0.04	0.02
A3	-	-	0.13
b	0.17	0.27	0.22
D	0.75	0.85	0.80
D2	0.15	0.35	0.25
E	0.75	0.85	0.80
E2	0.15	0.35	0.25
e	-	-	0.48
K	0.20	-	-
L	0.17	0.27	0.22
L1	0.02	0.12	0.07
Z	-	-	0.05
All Dimensions in mm			

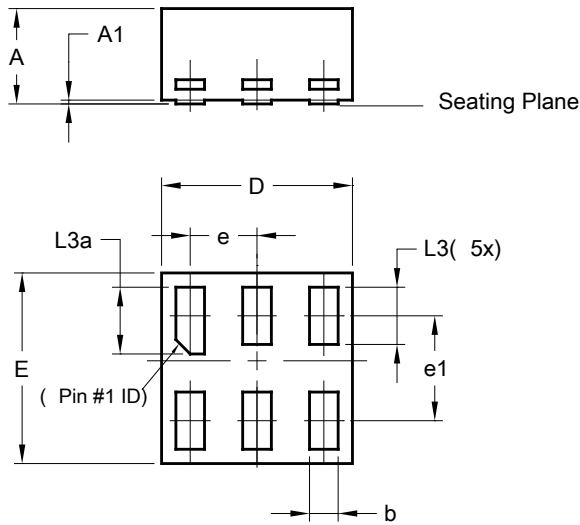


Dimensions	Value
C	0.480
X	0.320
X1	0.300
X2	0.106
X3	0.800
Y	0.320
Y1	0.300
Y2	0.106
Y3	0.900

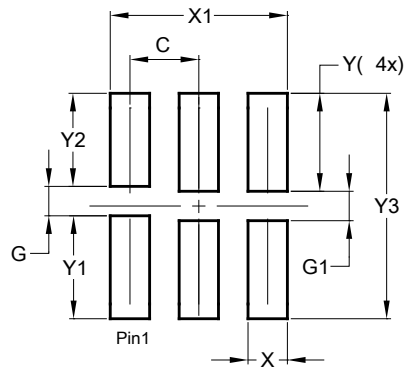
X2-DFN0808-4 Package Information  
Rev. 2015-06-05

**X1-DFN1010-6 (Type B) Package Outline Dimensions and Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version



X1-DFN1010-6 (Type B)			
Dim	Min	Max	Typ
A	-	0.50	0.39
A1	-	0.04	-
b	0.12	0.20	0.15
D	0.95	1.050	1.00
E	0.95	1.050	1.00
e	0.35 BSC		
e1	0.55 BSC		
L3	0.27	0.30	0.30
L3a	0.32	0.40	0.35
All Dimensions in mm			

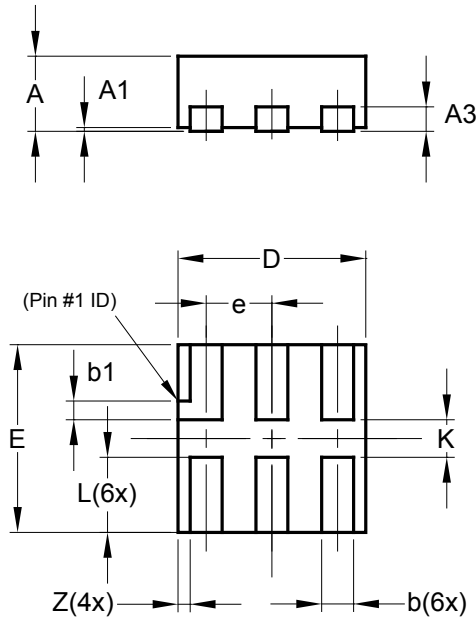


Dimensions	Value (in mm)
C	0.350
G	0.150
G1	0.150
X	0.200
X1	0.900
Y	0.500
Y1	0.525
Y2	0.475
Y3	1.150

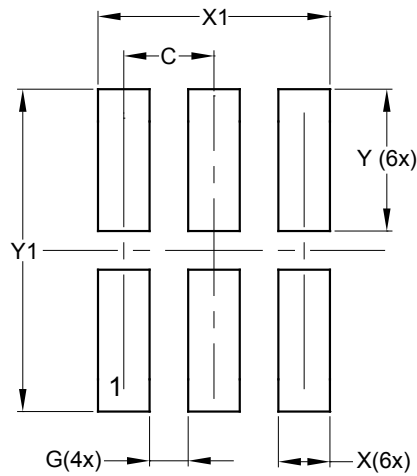
X1-DFN1010-6 (Type B) Package Information  
Rev. 2015-06-05

**X2-DFN1010-6 Package Outline Dimensions and Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version



X2-DFN1010-6			
Dim	Min	Max	Typ
A	—	0.40	0.39
A1	0.00	0.05	0.02
A3	—	—	0.13
b	0.14	0.20	0.17
b1	0.05	0.15	0.10
D	0.95	1.05	1.00
E	0.95	1.05	1.00
e	—	—	0.35
L	0.35	0.45	0.40
K	0.15	—	—
Z	—	—	0.065
All Dimensions in mm			

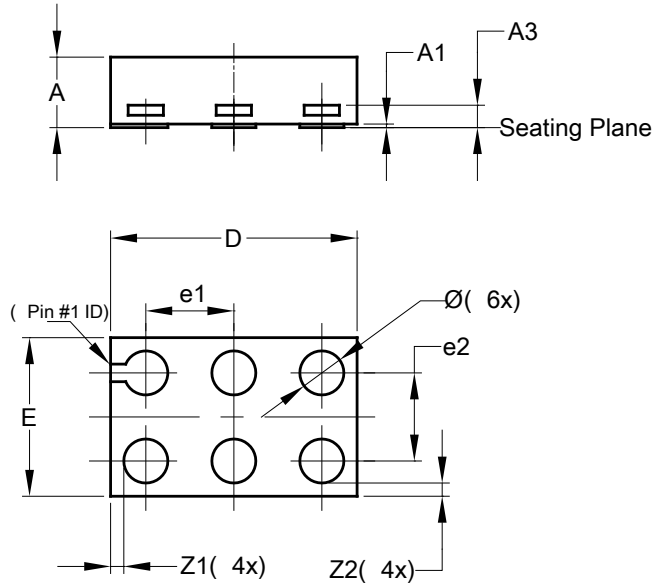


Dimensions	Value (in mm)
C	0.350
G	0.150
X	0.200
X1	0.900
Y	0.550
Y1	1.250

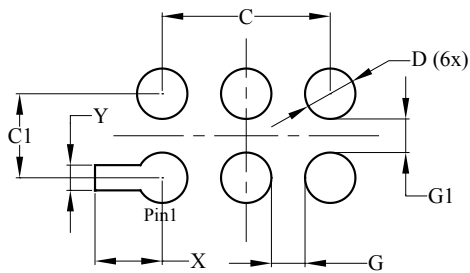
X2-DFN1010-6 Package Information  
Rev. 2018-07-17

**X2-DFN1409-6 Package Outline Dimensions and Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version



X2-DFN1409-6			
Dim	Min	Max	Typ
A	-	0.40	0.39
A1	0	0.05	0.02
A3	-	-	0.13
Ø	0.20	0.30	0.25
D	1.35	1.45	1.40
E	0.85	0.95	0.90
e1	-	-	0.50
e2	-	-	0.50
Z1	-	-	0.075
Z2	-	-	0.075
All Dimensions in mm			

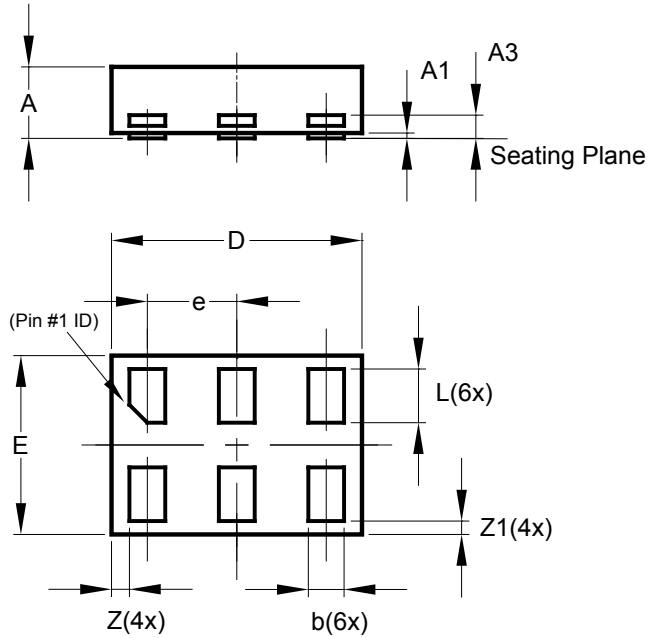


Dimensions	Value (in mm)
C	1.000
C1	0.500
D	0.300
G	0.200
G1	0.200
X	0.400
Y	0.150

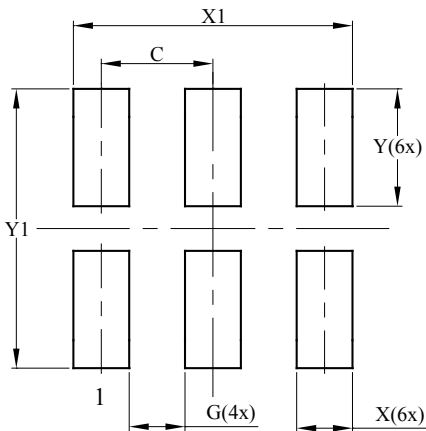
X2-DFN1409-6 Package Information  
Rev. 2018-07-17

**X2-DFN1410-6 Package Outline Dimensions and Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version



X2-DFN1410-6			
Dim	Min	Max	Typ
A	—	0.40	0.39
A1	0.00	0.05	0.02
A3	—	—	0.13
b	0.15	0.25	0.20
D	1.35	1.45	1.40
E	0.95	1.05	1.00
e	—	—	0.50
L	0.25	0.35	0.30
Z	—	—	0.10
Z1	0.045	0.105	0.075
All Dimensions in mm			



Dimensions	Value (in mm)
C	0.500
G	0.250
X	0.250
X1	1.250
Y	0.525
Y1	1.250

X2-DFN1410-6 Package Information  
Rev. 2015-06-08

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